

ABSTRACT

A porous film-forming composition comprising (A) a
5 curable silicone resin having a Mn of at least 100, (B) a
micelle-forming surfactant, and (C) a compound which
generates an acid upon pyrolysis remains stable during
storage. The composition is coated and heat treated to form
a porous film which has flatness, uniformity, a low
10 dielectric constant and a high mechanical strength so that it
is best suited as an interlayer dielectric film in the
fabrication of semiconductor devices.